



Insertion and chronic performance of ultra-fine neural electrode arrays in vivo

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Neurostimulation: respected family of therapies



Deep brain stimulation (DBS)

- Symptoms of Parkinson's disease
- Tremors
- Experimental: addiction, anorexia,...



Cochlear implants

- Nerve stimulation in the inner ear
- For helping the profoundly deaf
 - i.e. no functioning middle or outer ear

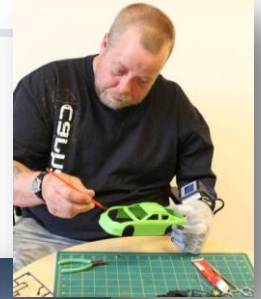
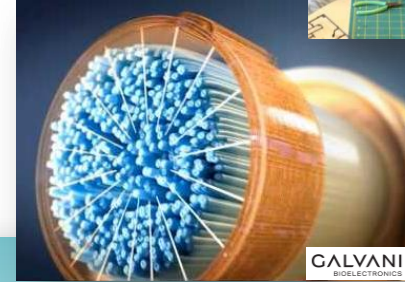
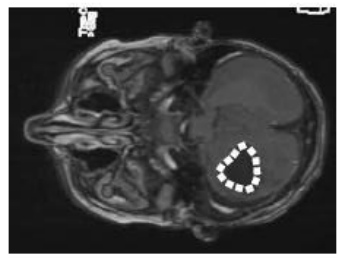


Pain relief



Near future applications needing higher resolution:

- 🤖 Advanced prosthetics
- 🤖 Electric medicine ('electroceuticals')
- 🤖 Artificial eyes
- 🤖 Communication with paralyzed
- 🤖 Neurostimulation in pathologic brain cavity



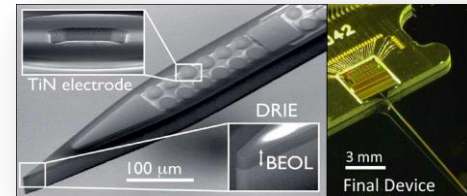
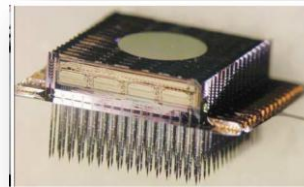
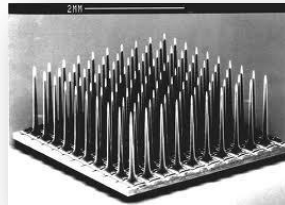
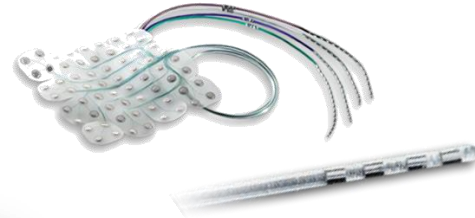
Common high electrode count implant types

🔧 Current clinical: silicone / PtIr

🔧 Microwire arrays

🔧 Silicon arrays

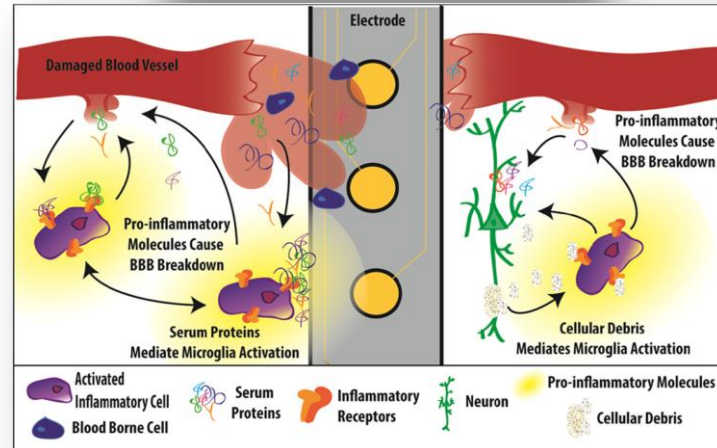
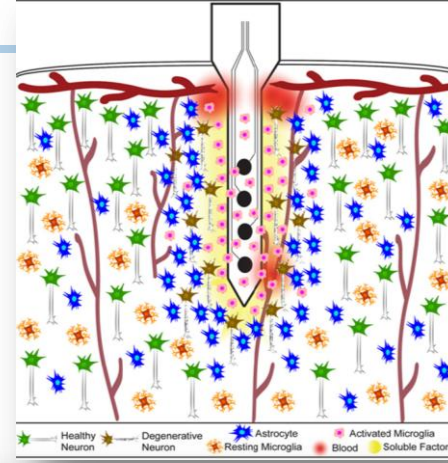
- Utah style
- Michigan style
- Si + integrated electronics



Scar formation: issue for long-term high-res interface

Mechanisms:

- Damage by insertion / relative movement of implant
- Blood-derived proteins activate inflammatory cells and stimulate the release of pro-inflammatory and cytotoxic cytokines-> Blood-brain barrier (BBB) breakdown.
- Release of pro-inflammatory and cytotoxic soluble => neuronal apoptosis. Cellular debris => further stimulate microglia activation and BBB instability
- Chronic inflammation and astrocytic encapsulation (glial scar)

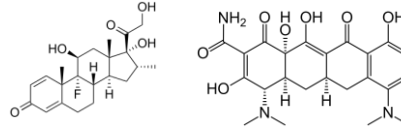


Strategies to reduce scar tissue formation



Anti-inflammatory drugs

- Dexamethasone, Minocyclin,...
- Optional: In situ drug release
- Not a long-term strategy



Reducing protein adhesion

- PLL-based coatings



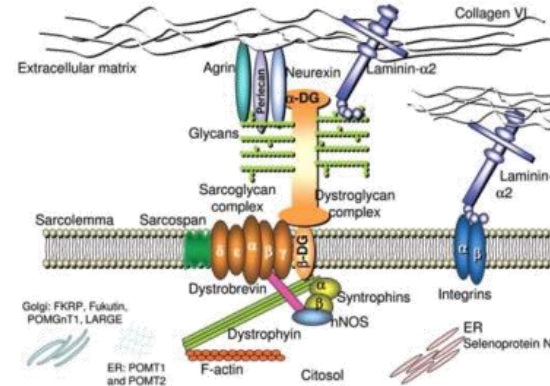
Bioactive coatings

- Laminin, L1, IKVAV
- Growth factor release



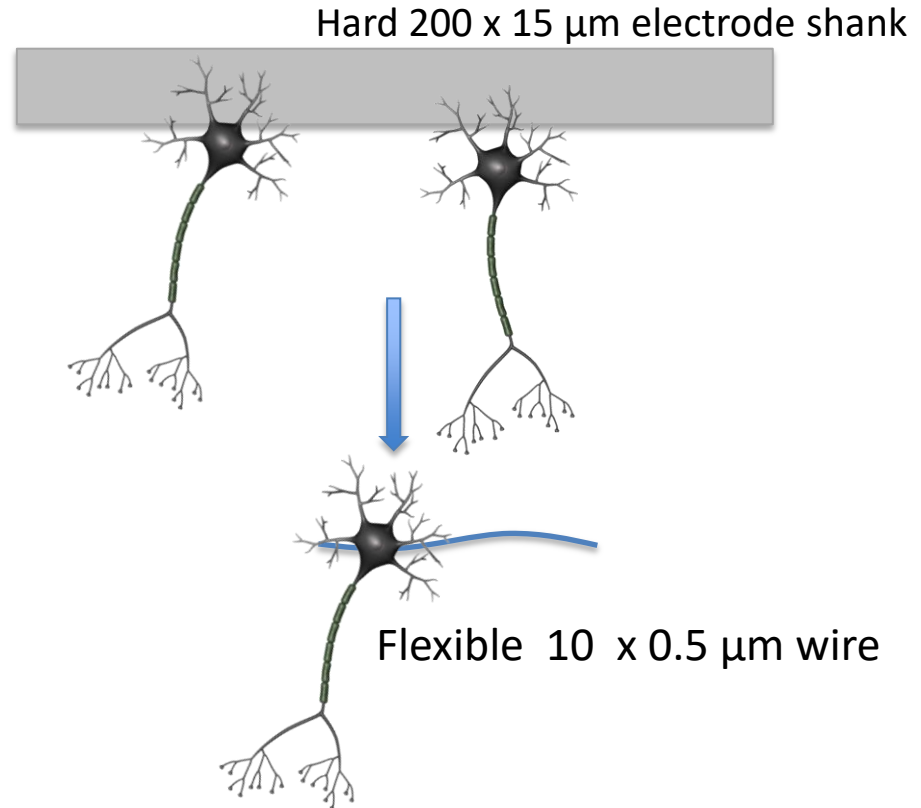
Reducing mechanical damage

- Avoiding firmly anchoring to skull
- Reducing cross sections
- Compliant materials
- Resorbable materials



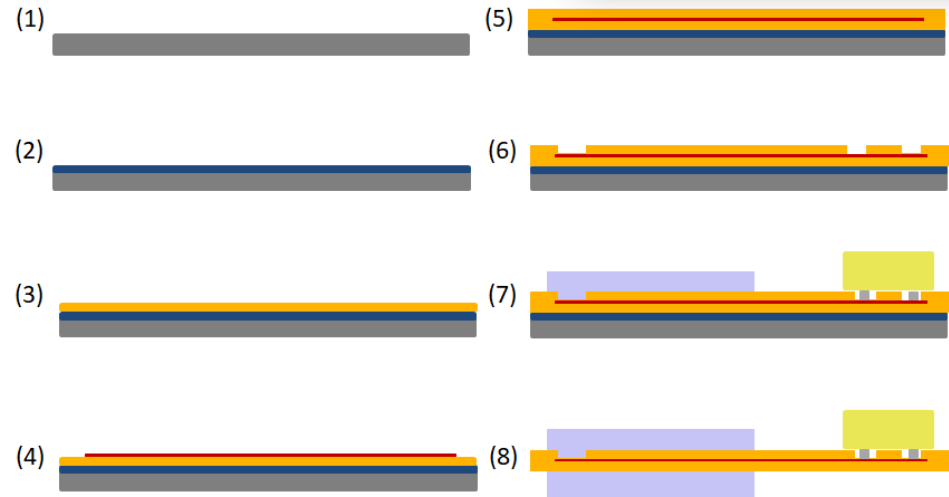
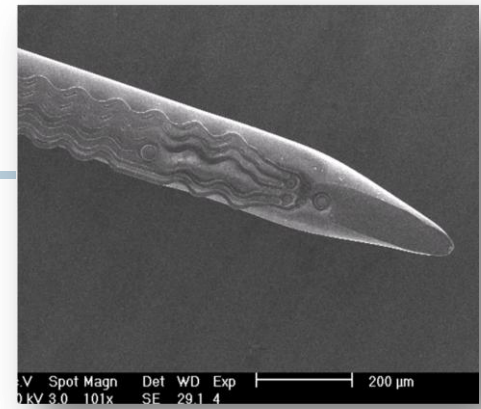
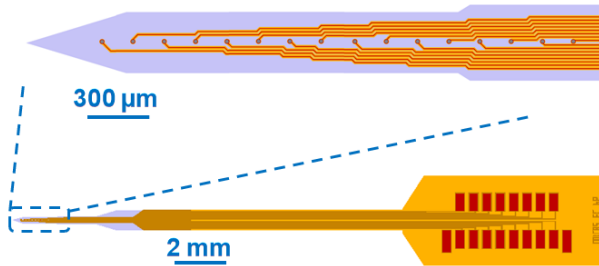
Our approach: ultra-flexible electrode arrays

- 1 μm thick
- Need relatively stiff needle-like carrier to get into the brain
- Carrier dissolves, only bare minimum stays behind
- Total dissolution must take ≤ 4 weeks [Turner 1999]



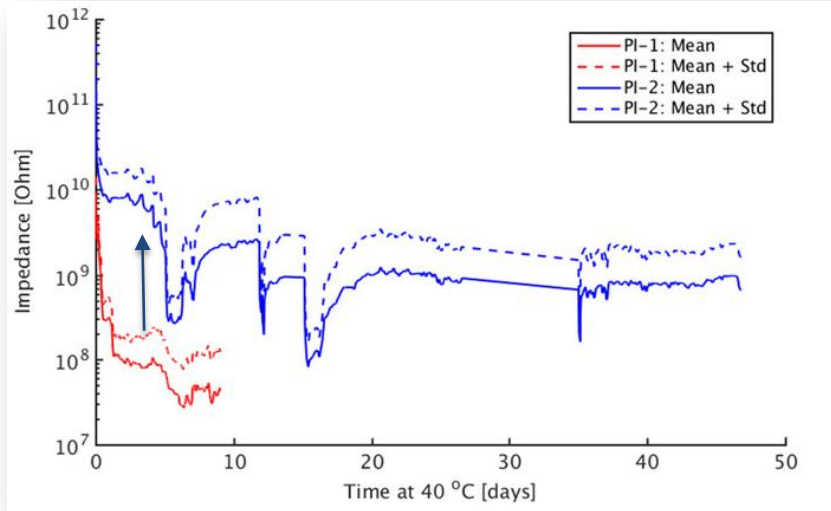
Design & Fabrication

- Wafer-scale, lithography based
- Polyimide isolation
- Pt metallization
- Iridium oxide electrodes
- Dissolving PLGA microneedle as carrier

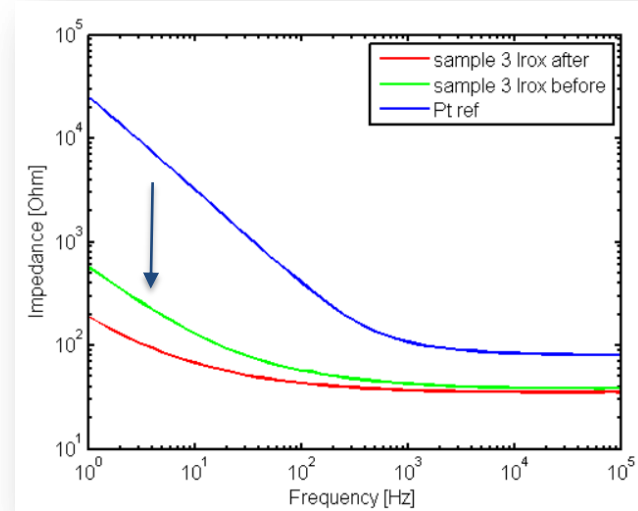


Si
 Al
 PI
 Pt
 Connector
 PLGA Microneedle

Implemented process improvements

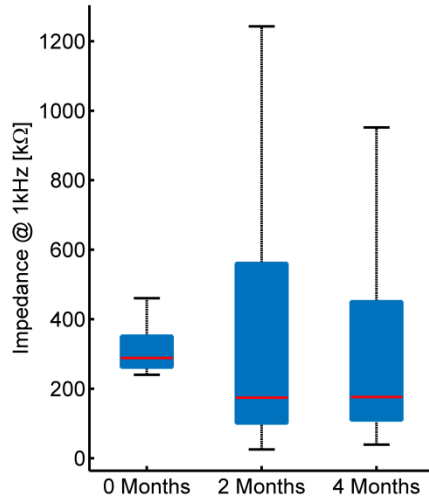
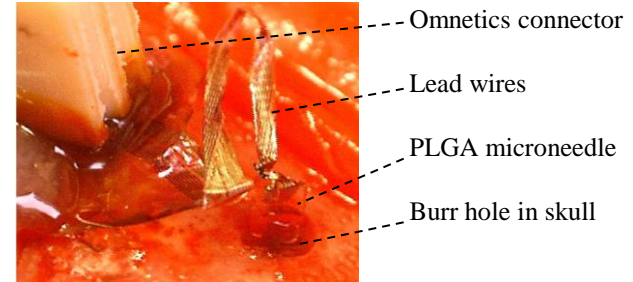


Improved leak impedance of isolation

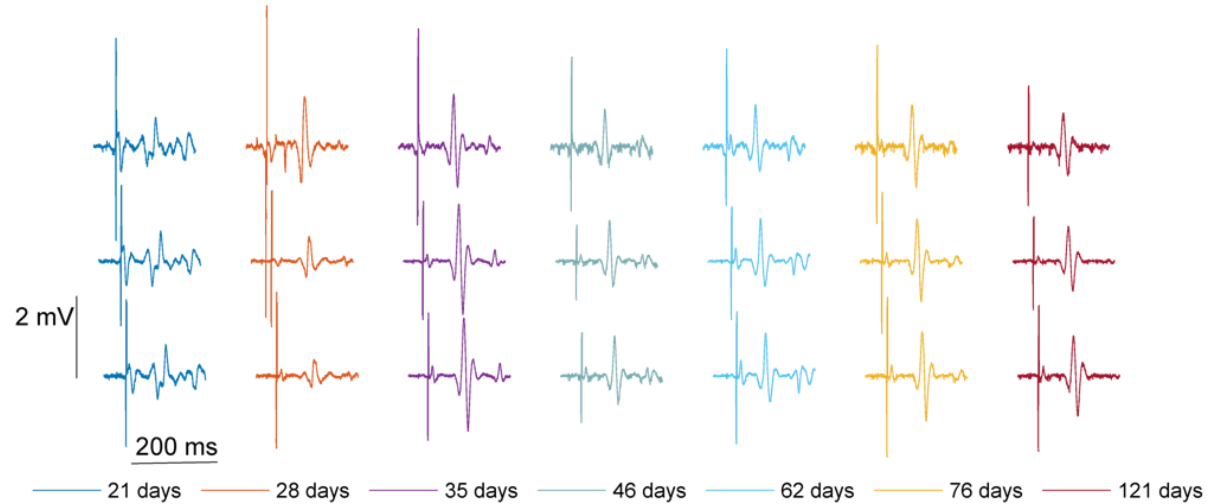


Reduced electrode impedance

In vivo tests in rats (4 months)



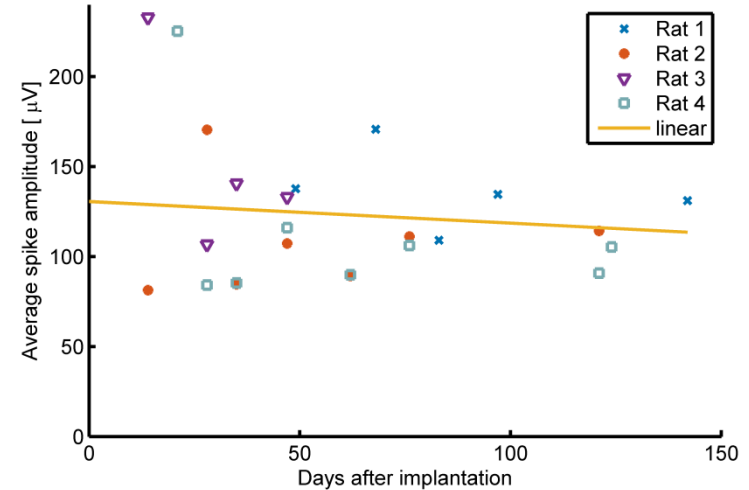
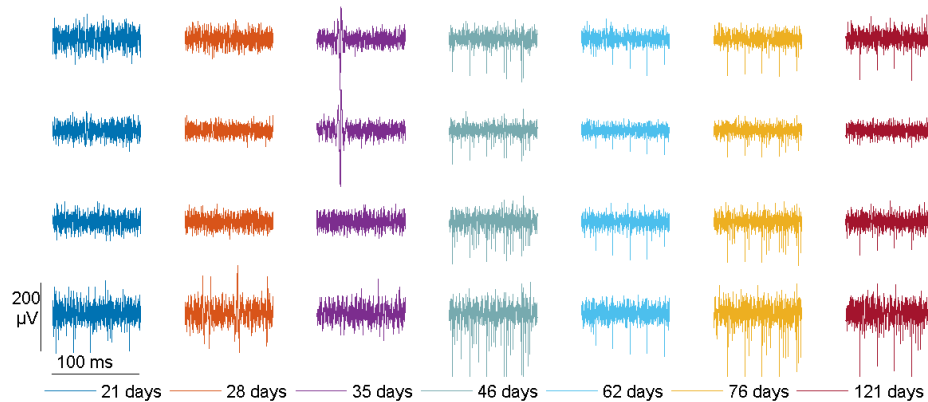
Stable impedance



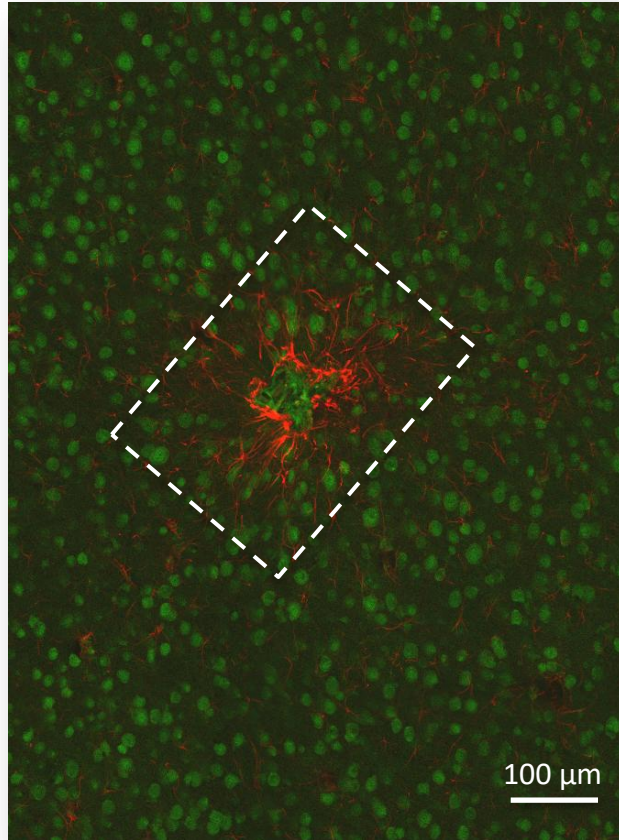
Stable evoked potential recording
(representative signals from 3 electrodes)

In vivo tests, part II

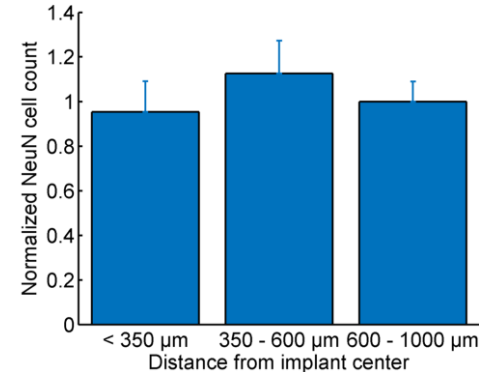
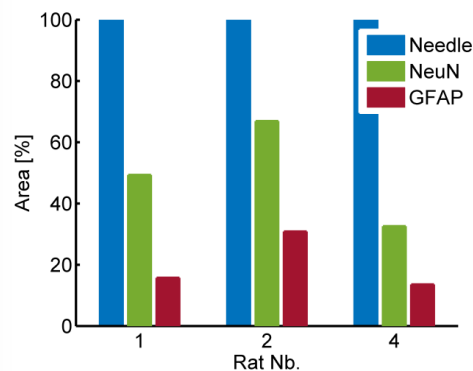
- Long term action potential recording possible (\leftrightarrow Si needles)
- After a 1 month incubation (needle dissolution)



Histology



- NeuN stain (green=viable neuron)
- GFAP stain (red = astrocytes)
- Scar only 20% of original needle
- Neurons grown into area formerly occupied by dissolving needle



Thanks!



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